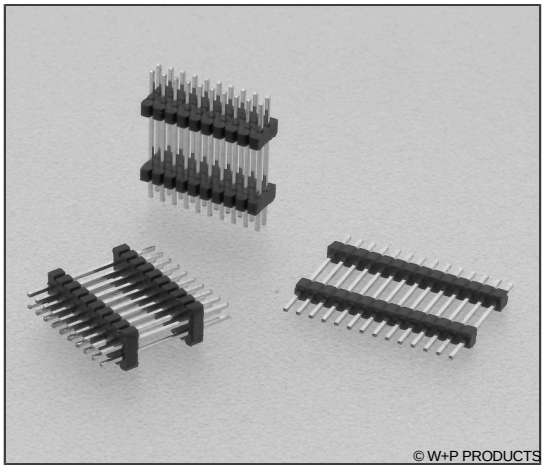
# 46-722 Economy Version

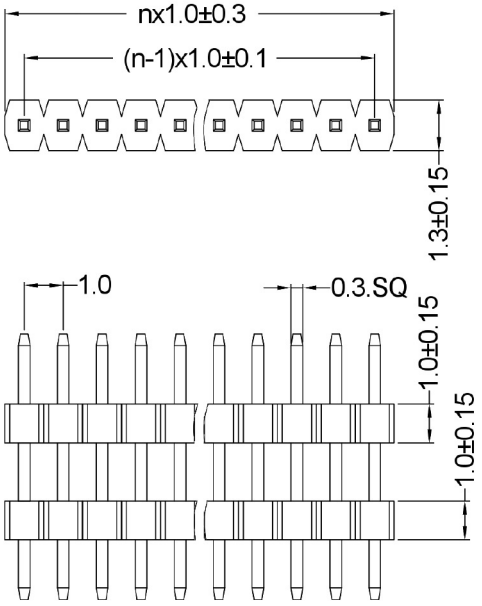
## Sandwich-Stiftleisten RM 1,00mm, 1-/2-reihig

***Dual Body Pin Headers, 1.00mm Pitch, Single/Double Row***

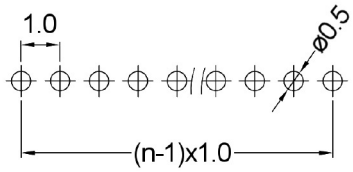
**Technische Daten /** ***Technical Data***

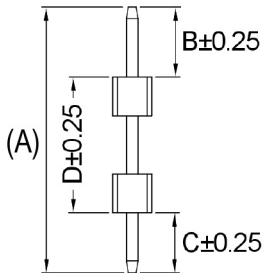
| | |
|---|---|
| Isolierkörper | Thermoplast, nach UL94 V-0 |
| *Insulator* | *Thermoplastic, rated UL94 V-0* |
| Kontaktmaterial | Kupferlegierung |
| *Contact Material* | *Copper alloy* |
| Kontaktoberfläche | Au über Ni |
| *Contact Surface* | *Au over Ni* |
| Durchgangswiderstand | < 30 mΩ |
| *Contact Resistance* | *< 30 mΩ* |
| Isolationswiderstand | > 500 MΩ |
| *Insulation Resistance* | *> 500 MΩ* |
| Spannungsfestigkeit | 500 V AC/DC |
| *Test Voltage* | *500 V AC/DC* |
| Nennstrom | 0,75 A |
| *Current Rating* | *0.75 A* |
| Temperaturbereich | -40 °C ~ +105 °C |
| *Temperature Range* | *-40 °C ~ +105 °C* |
| Verarbeitung | 260 °C für 10 sec. / 230 °C für 30~60 sec. |
| *Processing* | *260 °C for 10 sec. / 230 °C for 30~60 sec.* |




Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)




| ***Series*** | ***Contacts**** | ***Rows*** | ***Dimensions**** | ***Plating*** |
|---|---|---|---|---|
| **46-722** | **010** | **1** | **10** | **00** |
| | **001-050** Einreihig<br>*Single row* | **1** Einreihig<br>*Single row* | **10** B=2.00 C=2.50 D=6.50mm<br>**A [mm]** Andere Längen auf Anfrage<br>*Other lengths on request* | **00** Vergoldet<br>*Gold plated* |

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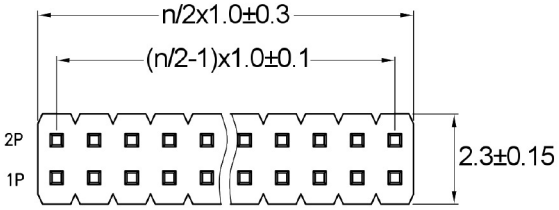
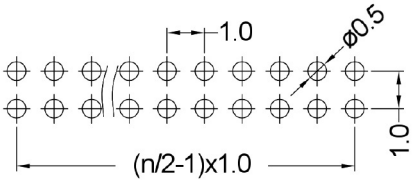
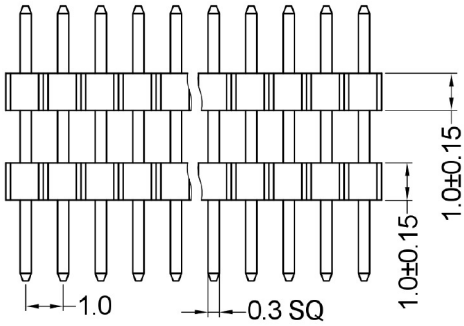
**Sandwich-Stiftleisten RM 1,00mm, 1-/2-reihig**

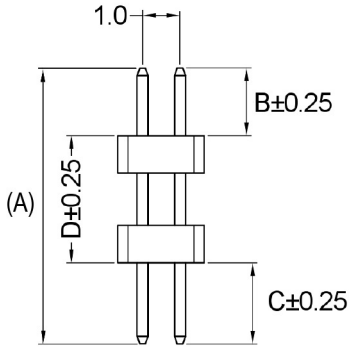
***Dual Body Pin Headers, 1.00mm Pitch, Single/Double Row***




Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)




| *Series* | *Contacts** | *Rows* | *Dimensions** | *Plating* |
|---|---|---|---|---|
| **46-722** | **020** | **2** | **10** | **00** |
| | **004-050** Zweireihig<br>*Double row* | **2** Zweireihig<br>*Double row* | **10** B=2.00 C=2.50 D=6.50mm<br>**A [mm]** Andere Längen auf Anfrage<br>*Other lengths on request* | **00** Vergoldet<br>*Gold plated* |

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
** This is an **order example** -*
*please replace by your specifications.*

## Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

| Profileigenschaft | Kennwert |
|---|---|
| Temperatur Minimum $T_S$min | 150 °C |
| Temperatur Maximum $T_S$max | 200 °C |
| Dauer $T_S$min – $T_S$max | 60 – 180s |
| Temperatur Lötbereich $T_L$ | untere Temperaturangabe [°C] |
| Verweildauer oberhalb $T_L$ | laut Angabe im Datenblatt [sec] |
| Ramp-Up Rate $T_S$max – $T_P$ | max. 3 °C / s |
| Höchsttemperatur $T_P$ | obere Temperaturangabe [°C] |
| Dauer Höchsttemperatur | laut Angabe im Datenblatt [sec] |
| Ramp-Down Rate $T_P$max – $T_S$min | 6 °C / s |
| Dauer 25 °C – Höchsttemperatur $T_P$ | max. 8m |

## Reflow Soldering Recommendation For Shorter Peak Times

*Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).*

| *Profile Feature* | Key Values |
|---|---|
| *Minimum Temperature $T_S$min* | *150 °C* |
| *Maximum Temperatur $T_S$max* | *200 °C* |
| *Duration $T_S$min – $T_S$max* | *60 – 180s* |
| *Soldering Range Temperature $T_L$* | *Lower Temperature [°C]* |
| *Duration above $T_L$* | *Acc. to datasheet [sec]* |
| *Ramp-Up Rate $T_S$max – $T_P$* | *max. 3 °C / s* |
| *Peak Temperature $T_P$* | *Upper Temperature [°C]* |
| *Duration Peak Temperature* | *Acc. to datasheet [sec]* |
| *Ramp-Down Rate $T_P$max – $T_S$min* | *6 °C / s* |
| *Duration 25°C - Peak Temp. $T_P$* | *max. 8min* |